Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
[List multiple models if applicable.]

HP 288 Pro G2 Microtower Business PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm MB, Memory, HDD PCA, ODD PCA, PSU PCA</td>
<td>5</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries MB</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>0</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>PSU</td>
<td>2</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Power cord</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td>system fan, Cooler fan, PSU fan</td>
<td>3</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
refractory ceramic fibers

Components, parts and materials containing radioactive substances 0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 crisscross screw driver</td>
<td>2#</td>
</tr>
<tr>
<td>Description #2 hexagon screw driver</td>
<td>T15</td>
</tr>
<tr>
<td>Description #3 electric iron</td>
<td>QUICK 310</td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove access panel from the unit.
2. Remove front panel from the unit.
3. Remove all the cable from the unit.
4. Remove HDD from the unit.
5. Remove ODD from the unit.
6. Take off PSU from the unit.
7. Take off the system fan from the unit.
8. Take off Card Reader from the unit.
9. Take off FIO from the unit.
10. Take off Memory from the unit.
11. Take off CPU cooler from the unit.
12. Take off PCA from the unit.
13. Take off battery from the unit.
14. Open the PSU.
15. Take off PSU fan.
16. Take off PCA from the PSU.
17. Take off CAP using electric iron.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
1. Remove access panel from the unit.

Release screw on the access panel. Griping the tab at the end of access panel, pull towards the rear and remove it from unit.
2. Remove front panel from the unit.

Release 3 bezellatches from chassis by pulling the bezellatches outwards.

3. Remove all the cable from the unit.

4. Remove HDD from the
5. Remove ODD from the unit.
6. Take off PSU from the unit.

Rotate the screw driver to
7. Take off the system fan from the unit

Rotate screw driver to loose screw and take off the release PSU from the unit.
8. Take off Card Reader from the unit.
9. Take off FIO from the unit.

10. Take off Memory from the unit.

Release memory socket levers by pulling outward.

11. Take off CPU cooler from the unit.
Rotate the screw driver to release CPU cooler from the unit.

12. Take off PCA from the unit.

Rotate screw driver to loose PCA from the unit.
13. Take off battery from the unit.

14. Open the PSU
   Rotate screw driver to release PSU cover.

15. Take off PSU fan.
16. Take off PCA from the PSU.

Rotate the screw driver to release the PCA from PSU.

17. Take off CAP using electric iron.